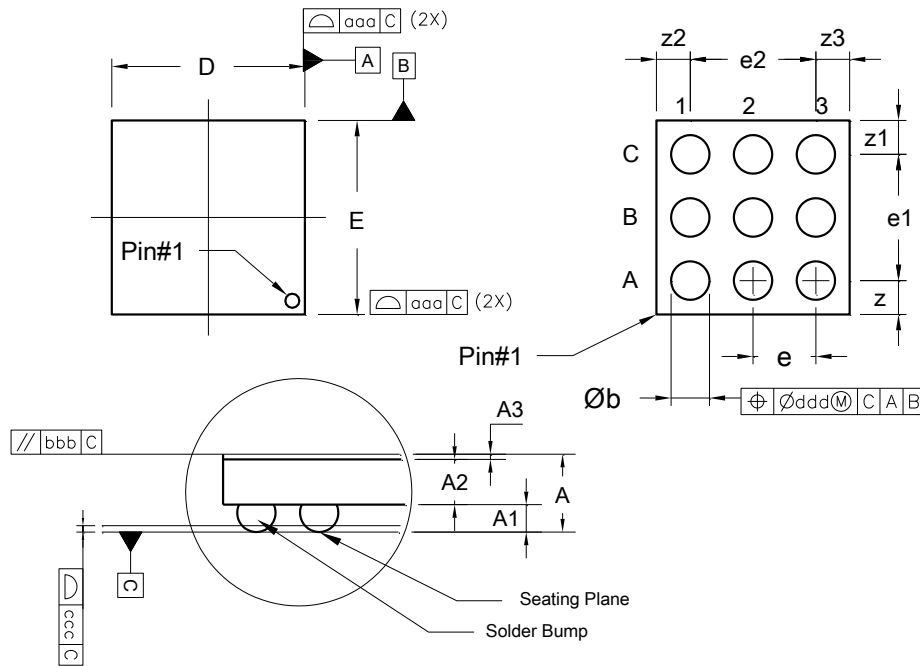


Package Outline Dimensions

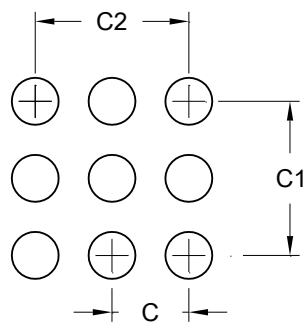
X1-WLB0909-9 (Type A1)



X1-WLB0909-9 (Type A1)			
Dim	Min	Max	Typ
A	0.3290	0.4110	0.3700
A1	0.1170	0.1430	0.1300
A2	0.1900	0.2400	0.2150
A3	0.0220	0.0280	0.0250
b	0.1556	0.2105	0.1830
D	0.8950	0.9500	0.9225
E	0.8950	0.9500	0.9225
e	--	--	0.3000
e1	--	--	0.6000
e2	--	--	0.6000
z	--	--	0.1613
z1	--	--	0.1613
z2	--	--	0.1613
z3	--	--	0.1613
aaa	--	--	0.0275
bbb	--	--	0.0600
ccc	--	--	0.0300
ddd	--	--	0.1500
All Dimensions in mm			

Suggested Pad Layout

X1-WLB0909-9 (Type A1)



Dimensions	Value (in mm)
C	0.3000
C1	0.6000
C2	0.600
D	0.1830

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.